

MJD117

/ Descriptions

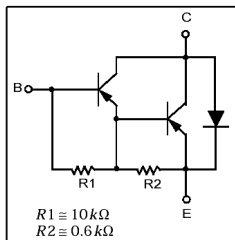
TO-252 PNP

/ Features

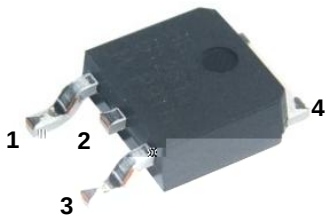
E C TIP117

/ Applications

/ Equivalent Circuit

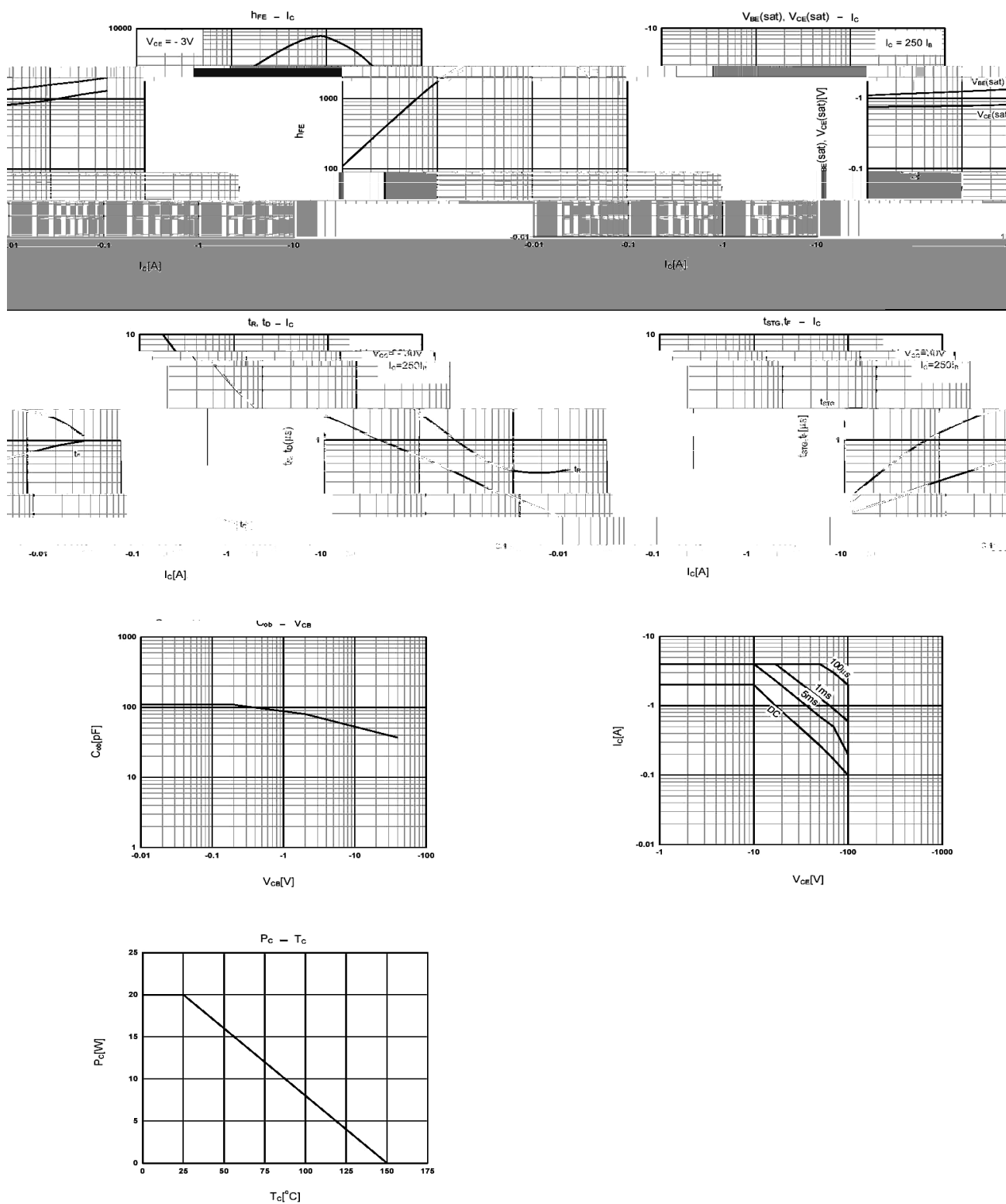


/ Pinning

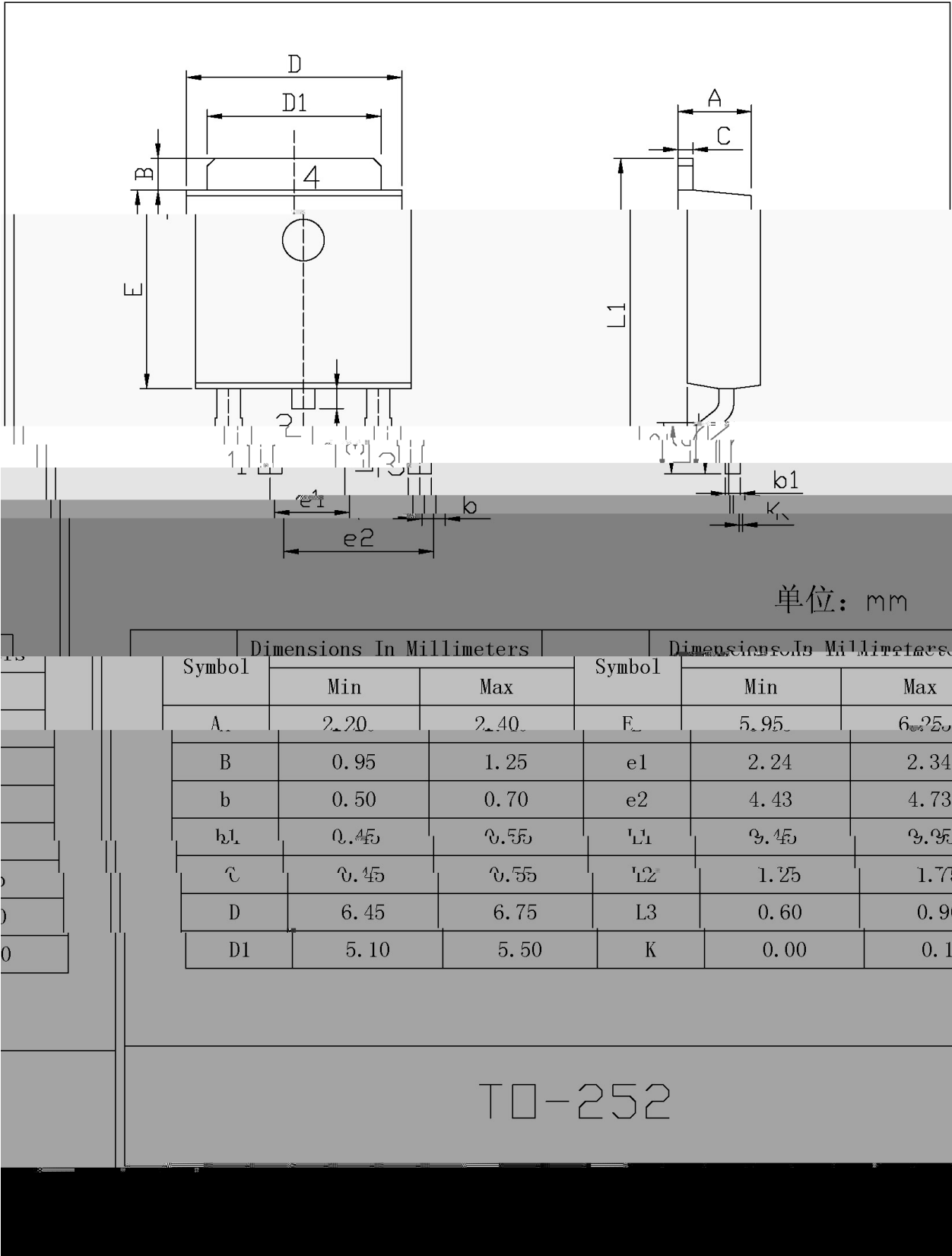


/ h_{FE} Classifications & Marking

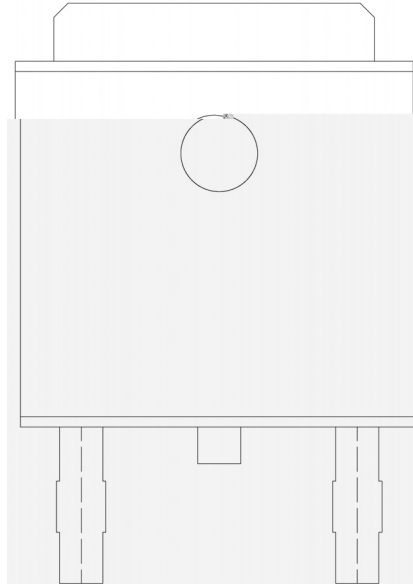
/ Electrical Characteristic Curve



/ Package Dimensions

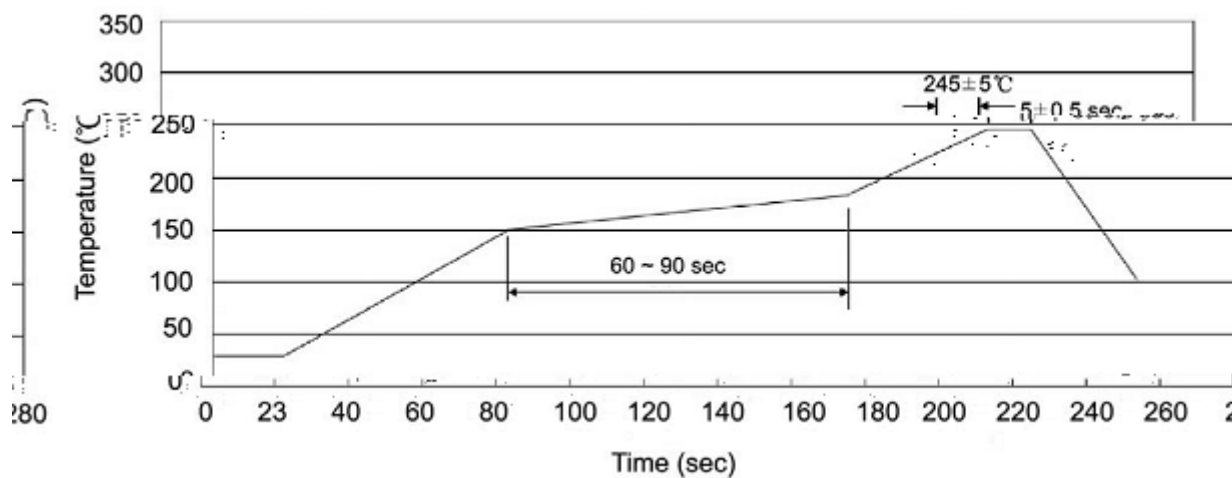


/ Marking Instructions



MJD117

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

 $\pm$ $\pm$ $\pm$ $\pm$

/ Resistance to Soldering Heat Test Conditions

 $\pm$ $\pm$

°C

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

封装形式	包装数量					包装尺寸		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices